

Special Issue

Advances in Additive Manufacturing and Topology Optimization

Message from the Guest Editors

Numerical tools have been developed during the last few years, but the quality of the obtained results is unknown. An additional question which must be addressed is how to obtain the data to feed multi-physics models. This Special Issue collects original articles addressing the design methods, monitoring and modelling of additive manufacturing processes and the mechanical behavior of the manufactured parts. Both theoretical and experimental contributions are welcome, as well as research papers or reviews.

Guest Editors

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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